EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3	"580740".ap.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 13:41
L2	8	("20020072215" | "20040018660" | "5160409" | "6316831").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 14:21
L3	1733	("205"/$.ccls. "204"/$.ccls. "438"/$.ccls. "257"/$.ccls. "216"/$.ccls.) and (electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and solder near3 bump and $5resist and barrier	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 14:33
L4	472	("205"/$.ccls. "204"/$.ccls. "438"/$.ccls. "257"/$.ccls. "216"/$.ccls.) and (electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and solder near3 bump and $5resist and barrier and seed and copper and nickel	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 14:34
L5	460	("205"/$.ccls. "204"/$.ccls. "438"/$.ccls. "257"/$.ccls. "216"/$.ccls.) and (electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and solder near3 bump and $5resist and barrier and seed and copper and nickel and etch$4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 14:34

L6	198	("205"/$.ccls. "204"/$.ccls. "438"/$.ccls. "257"/$.ccls. "216"/$.ccls.) and (electrolytic electrochemic$4 electrodeposit$5 electroplat$5) same solder near3 bump and $5resist and barrier and seed and copper and nickel and etch$4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 14:36
L7	190	("205"/$.ccls. "204"/$.ccls. "438"/$.ccls. "257"/$.ccls. "216"/$.ccls.) and (electrolytic electrochemic$4 electrodeposit$5 electroplat$5) same solder near3 bump and $5resist and barrier and seed and copper and nickel and etch$4 same (seed barrier copper)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 14:37
L8	40	("20020068425" | "20020079576" | "20020190028" | "20030057551" | "5268072" | "5492235" | "5503286" | "5543032" | "5629564" | "5767010" | "5800726" | "5855993" | "5885891" | "5937320" | "6162652" | "6187680" | "6222279" | "6277669" | "6293457" | "6319846" | "6332988" | "6333559" | "6358836" | "6489229" | "6501185" | "6536653" | "6541366").PN. OR ("6622907").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/03/02 14:47

L10	17	("205"/$.ccls. "204"/$.ccls. "438"/$.ccls. "257"/$.ccls. "216"/$.ccls.) and (electrolytic electrochemic$4 electrodeposit$5 electroplat$5) same solder near3 bump and $5resist and barrier and seed and copper and nickel and etch$4 same (seed barrier copper) and current adj2 density	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 16:16
L11	4	("205"/$.ccls. "204"/$.ccls. "438"/$.ccls. "257"/$.ccls. "216"/$.ccls.) and (electrolytic electrochemic$4 electrodeposit$5 electroplat$5) same solder near3 bump and $5resist and barrier and seed and copper and nickel and (current adj2 density) with (increas$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 16:22
L12	3	("205"/$.ccls. "204"/$.ccls. "438"/$.ccls. "257"/$.ccls. "216"/$.ccls.) and (electrolytic electrochemic$4 electrodeposit$5 electroplat$5) same solder near3 bump and $5resist and barrier and seed and copper and nickel and (current adj2 density) near5 (increas$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 16:23
L13	0	("205"/$.ccls. "204"/$.ccls. "438"/$.ccls. "257"/$.ccls. "216"/$.ccls.) and (electrolytic electrochemic$4 electrodeposit$5 electroplat$5) same solder near3 bump and $5resist and barrier and seed and (current adj2 density) near5 (increas$3) with rate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 16:28

L14	0	("205"/$.ccls. "204"/$.ccls. "438"/$.ccls. "257"/$.ccls. "216"/$.ccls.) and (electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and solder near3 bump and $5resist and barrier and seed and (current adj2 density) near5 (increas$3) with rate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 16:28
L15	13	("205"/$.ccls. "204"/$.ccls. "438"/$.ccls. "257"/$.ccls. "216"/$.ccls.) and (electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and $5resist and barrier and seed and (current adj2 density) near5 (increas$3) with rate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 16:29
L16	4	("205"/$.ccls. "204"/$.ccls. "438"/$.ccls. "257"/$.ccls. "216"/$.ccls.) and (electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and solder and $5resist and (current adj2 density) near5 (increas$3) with rate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 16:36
L17	487	("205"/$.ccls. "204"/$.ccls. "438"/$.ccls. "257"/$.ccls. "216"/$.ccls.) and (electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and (current adj2 density) near5 (increas$3) with rate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 16:40

L18	16	("205"/$.ccls. "204"/$.ccls. "438"/$.ccls. "257"/$.ccls. "216"/$.ccls.) and (electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and solder and (current adj2 density) near5 (increas$3) with rate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 16:40
L19	11	("205"/$.ccls. "204"/$.ccls. "438"/$.ccls. "257"/$.ccls. "216"/$.ccls.) and (electrolytic electrochemic$4 electrodeposit$5 electroplat$5) and bump and (current adj2 density) near5 (increas$3) with rate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 16:44

3/2/2009 6:12:39 PM
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